

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
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Property Type	Number	
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Total Attachments: 1		
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ASSIGNMENT

This is an Assignment of the following rights, title and interest:

- ☐ United States of America rights, title and interest in the invention
- ☐ Foreign rights, title and interest in the invention
- ☒ International Application No. PCT/JP2018/035932
- Date of Filing: September 27, 2018
- ☐ For which an application for a U.S. Patent was executed on _____
- ☐ United States Patent Application Serial No. _____
- Date of Filing: _____

Title of the Invention:

SOLDER ALLOY, SOLDER JOINT MATERIAL,
AND ELECTRONIC CIRCUIT BOARD

Inventors (Assignors): Takehiro WADA c/o KOKI Company Limited, 32-1, Senju Asahi-cho,
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Assignee(s): KOKI Company Limited of 32-1, Senju Asahi-cho, Adachi-ku, Tokyo
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Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified assignee;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said applications(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States, unto said Assignee.

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.


Signature: Takehiro WADA

July 25, 2019
Date